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United States Patent

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(12) **United States Patent**
Chung et al.

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(54) **LIGHT-MIXING MULTICHIP PACKAGE STRUCTURE**

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See application file for complete search history.

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(*) Notice: Subject to any disclaimer, the term of this patent is extended or adjusted under 35 U.S.C. 154(b) by 0 days.

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(57) **ABSTRACT**

A light-mixing multichip package structure includes a circuit substrate, a first light-emitting module, a first package body, a second light-emitting module and a second package body. The first light-emitting module includes a plurality of first light-emitting elements disposed on the circuit substrate and electrically connected to the circuit substrate. The first package body is disposed on the circuit substrate to enclose the first light-emitting elements. The second light-emitting module includes a plurality of second light-emitting elements disposed on the circuit substrate and electrically connected to the circuit substrate, and the first light-emitting module and the first package body are surrounded by the second light-emitting elements. The second package body is disposed on the circuit substrate to enclose the first light-emitting module, the second light-emitting module and the first package body.

(52) **U.S. Cl.**
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10 Claims, 8 Drawing Sheets

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